

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
8 March 2007 (08.03.2007)

PCT

(10) International Publication Number
WO 2007/027401 A2

(51) International Patent Classification:
B23K 3/06 (2006.01)

(21) International Application Number:
PCT/US2006/031309

(22) International Filing Date: 11 August 2006 (11.08.2006)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
11/215,214 30 August 2005 (30.08.2005) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

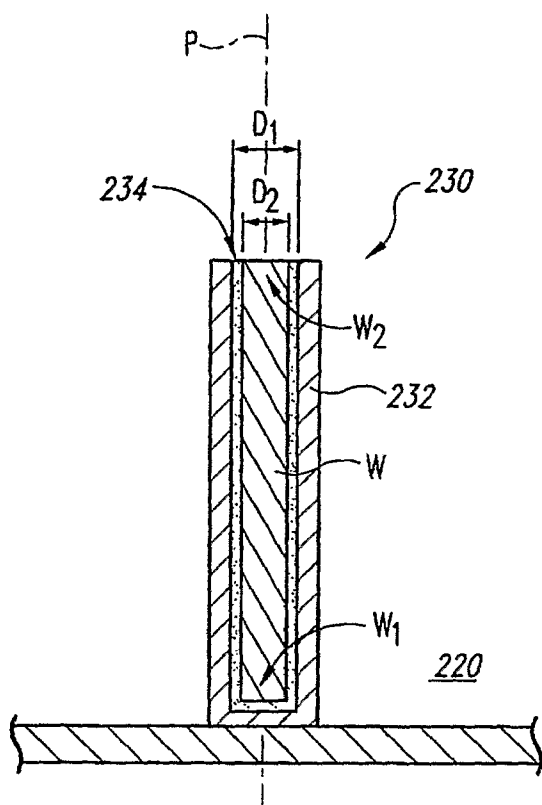
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: SYSTEMS AND METHODS FOR DEPOSITING CONDUCTIVE MATERIAL INTO OPENINGS IN MICROFEATURE WORKPIECES



(57) Abstract: Systems and methods for depositing conductive material into openings in microfeature workpieces are disclosed herein. One particular embodiment of a system for processing microfeature workpieces includes a processing chamber and a solder reservoir in the processing chamber. The solder reservoir includes a slot having a generally vertical orientation positioned to receive a microfeature workpiece. In several embodiments, the system can further include a conductive material at least partially filling the slot.

WO 2007/027401 A2